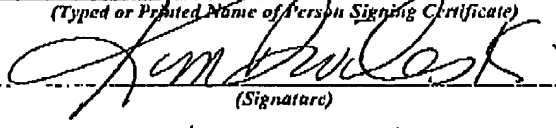


CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)			Docket No. END920010135US2
Applicant(s): Alcoe et al.			
Application No. 10/665,669	Filing Date 9/18/2003	Examiner Thao, X. Le	Group Art Unit 2814
Invention: THERMALLY ENHANCED LID FOR MULTI-CHIP MODULES			
RECEIVED CENTRAL FAX CENTER MAY 17 2005			
I hereby certify that this <u>Request for Reconsideration (12 pages)</u> (Identify type of correspondence)			
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.: 10/665,669

Applicant(s): Alcoe et al.

Filed.: September 18, 2003

Art Unit: 2814

Dkt. No.: END920010135US2

Examiner: Le, Thao X.

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MAY 17 2005**Title: THERMALLY ENHANCED LID FOR MULTI-CHIP MODULES**

Honorable Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

REQUEST FOR RECONSIDERATION

This Request for Reconsideration is being filed in response to the Final Office Action mailed on March 23, 2005. Applicants request this Amendment be entered in the above-identified application and reconsideration of the application in view of the Amendments and Remarks that follow.